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BLC9G20XS-550AVT

Power LDMOS transistor

AMPLEON

Rev. 2 — 2 December 2016

Product data sheet

1. Product profile

1.1 General description

550 W LDMOS packaged asymmetric Doherty power transistor for base station applications at frequencies from 1805 MHz to 1880 MHz.

Table 1. Typical performance

Typical RF performance at T_{case} = 25 °C in an asymmetrical Doherty production test circuit. V_{DS} = 28 V; I_{Dq} = 1100 mA (main); $V_{GS(amp)peak}$ = 0.7 V, unless otherwise specified.

Test signal	f	V _{DS}	P _{L(AV)}	G _p	η_D	ACPR
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
1-carrier W-CDMA	1805 to 1880	28	85	15.4	44.5	-34 <u>[1]</u>

^[1] Test signal: 1-carrier W-CDMA; 3GPP test model 1; 64 DPCH; PAR = 9.6 dB at 0.01 % probability on CCDF.

1.2 Features and benefits

- Excellent ruggedness
- High-efficiency
- Low thermal resistance providing excellent thermal stability
- Lower output capacitance for improved performance in Doherty applications
- Designed for low memory effects providing excellent digital pre-distortion capability
- Internally matched for ease of use
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

1.3 Applications

RF power amplifiers for base stations and multi carrier applications in the 1805 MHz to 1880 MHz frequency range

2. Pinning information

Table 2. Pinning

Pin	Description		Simplified outline	Graphic symbol
1	drain2 (peak)		- 0 4 -	0.7
2	drain1 (main)		7 2 1 6	2, 7
3	gate1 (main)		5	<u> </u>
4	gate2 (peak)		3 4	3——5
5	source	[1]		4—
6	video decoupling (peak)			" ¬
7	video decoupling (main)			1, 6 aaa-014884

^[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Package				
	Name	Description	Version		
BLC9G20XS-550AVT	-	air cavity plastic earless flanged package; 6 leads	SOT1258-7		

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	65	V
V _{GS(amp)main}	main amplifier gate-source voltage		-6	+13	V
V _{GS(amp)peak}	peak amplifier gate-source voltage		-6	+13	V
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature	[1]	-	225	°C
T _{case}	case temperature	operating [1]	-4 0	+125	°C

^[1] Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-c)}		V_{DS} = 28 V; I_{Dq} = 1100 mA (main); $V_{GS(amp)peak}$ = 0,5 V; T_{case} = 80 °C		
		P _L = 85 W	0.27	k/W
		P _L = 110 W	0.27	k/W

BLC9G20XS-550AVT

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6. Characteristics

Table 6. DC characteristics

 T_i = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit				
Main dev	Main device									
V _{(BR)DSS}	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 2.2 \text{ mA}$	65	-	-	V				
V _{GS(th)}	gate-source threshold voltage	V _{DS} = 10 V; I _D = 220 mA	1.5	2.0	2.5	V				
V_{GSq}	gate-source quiescent voltage	V _{DS} = 28 V; I _D = 1000 mA	1.65	2.15	2.65	V				
I _{DSS}	drain leakage current	V _{GS} = 0 V; V _{DS} = 32 V	-	-	2.8	μА				
I _{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 V$	-	40	-	Α				
I _{GSS}	gate leakage current	V _{GS} = 11 V; V _{DS} = 0 V	-	-	280	nA				
g _{fs}	forward transconductance	V _{DS} = 10 V; I _D = 11 A	-	14.5	-	S				
R _{DS(on)}	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $I_D = 7.7 \text{ A}$	-	69	112	mΩ				
Peak dev	rice									
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 3.6 \text{ mA}$	65	-	-	V				
V _{GS(th)}	gate-source threshold voltage	V _{DS} = 10 V; I _D = 360 mA	1.5	2.0	2.5	V				
V_{GSq}	gate-source quiescent voltage	V _{DS} = 28 V; I _D = 1800 mA	1.65	2.15	2.65	V				
I _{DSS}	drain leakage current	V _{GS} = 0 V; V _{DS} = 32 V	-	-	2.8	μА				
I _{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 V$	-	65	-	Α				
I _{GSS}	gate leakage current	V _{GS} = 11 V; V _{DS} = 0 V	-	-	280	nA				
g _{fs}	forward transconductance	V _{DS} = 10 V; I _D = 18 A	-	23	-	S				
R _{DS(on)}	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $I_D = 12.6 \text{ A}$	-	44	72	mΩ				

Table 7. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1 to 64 DPCH; f_1 =1807.5 MHz; f_2 = 1877.5 MHz; RF performance at V_{DS} = 28 V; I_{Dq} = 1000 mA (main); $V_{GS(amp)peak}$ = 0.7 V; T_{case} = 25 °C; unless otherwise specified; in an asymmetrical Doherty production test circuit at frequencies from 1805 MHz to 1880 MHz.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Gp	power gain	P _{L(AV)} = 85 W	14.6	15.4	-	dB
RLin	input return loss	P _{L(AV)} = 85 W	-	-15	-10	dB
η_{D}	drain efficiency	P _{L(AV)} = 85 W	40.5	44.5	-	%
ACPR	adjacent channel power ratio	P _{L(AV)} = 85 W	-	-34	-29	dBc

Table 8. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1 to 64 DPCH; f = 1877.5 MHz; RF performance at V_{DS} = 28 V; I_{Dq} = 1000 mA (main); $V_{GS(amp)peak}$ = 0.7 V; T_{case} = 25 °C; unless otherwise specified; in an asymmetrical Doherty production test circuit at a frequency of 1880 MHz.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
PARO	output peak-to-average ratio	P _{L(AV)} = 120 W	6.4	7.0	-	dB
$P_{L(M)}$	peak output power	P _{L(AV)} = 120 W	492	580	-	W

7. Test information

7.1 Ruggedness in Doherty operation

The BLC9G20XS-550AVT is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions: V_{DS} = 28 V; I_{Dq} = 1000 mA; $V_{GS(amp)peak}$ = 0.7 V; f = 1807.5 MHz; P_L = 174 W (5 dB OBO); 100 % clipping.

7.2 Impedance information

Table 9. Typical impedance of main device

Measured load-null data of main device: In = 1100 mA (main): Voc = 28 V: nuls

Measured load-pull data of main device; I_{Dq} = 1100 mA (main); V_{DS} = 28 V; pulsed CW (t_p = 100 μ s; δ = 10 %).

f	Z _S [1]	Z _L [1]	P _L [2]	η _D [2]	G _p [2]					
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)					
Maximum	Maximum power load									
1805	1.7 – j6.1	1.4 – j3.5	275	58.0	18.5					
1840	2.3 – j6.6	1.5 – j3.4	270	61.2	19.3					
1880	3.1 – j6.9	1.5 – j3.0	240	61.4	20.2					
Maximun	n drain efficiency	load								
1805	1.7 – j6.1	2.2 – j2.3	210	67.8	20.8					
1840	2.3 – j6.6	2.2 – j2.3	200	67.2	21.2					
1880	3.1 – j6.9	2.0 – j2.6	210	65.7	21.0					

^[1] Z_S and Z_L defined in Figure 1.

^[2] At 3 dB gain compression.

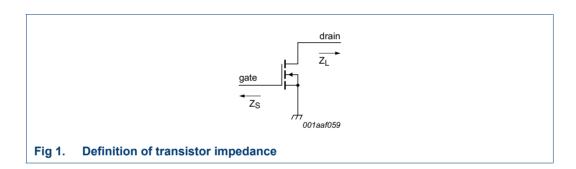
Table 10. Typical impedance of peak device

Measured load-pull data of peak device; I_{Dq} = 2200 mA (peak); V_{DS} = 28 V; pulsed CW (t_p = 100 μ s; δ = 10 %).

f	Z _S [1]	Z _L [1]	P _L [2]	η _D [2]	G _p [2]					
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)					
Maximum	Maximum power load									
1805	1.7 – j6.1	1.2 – j3.5	425	58.2	18.0					
1840	2.4 – j6.6	1.2 – j3.5	415	57.9	18.3					
1880	3.4 – j7.1	1.4 – j3.6	405	59.1	18.6					
Maximum	n drain efficiency	load								
1805	1.7 – j6.1	1.8 – j2.3	290	65.8	20.3					
1840	2.4 – j6.6	1.6 – j2.6	320	65.1	20.1					
1880	3.4 – j7.1	1.8 – j2.5	285	64.6	20.4					

^[1] Z_S and Z_L defined in Figure 1.

^[2] At 3 dB gain compression.



7.3 Recommended impedances for Doherty design

Table 11. Typical impedance of main at 1:1 load

Measured load-pull data of main device; I_{Dq} = 1100 mA (main); V_{DS} = 28 V; pulsed CW (t_p = 100 μ s; δ = 10 %).

f	Z _S [1]	Z _L [1]	P _{L(3dB)} [2]	η _D [2]	G _p [2]
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)
1805	1.6 – j6.1	1.7 – j3.7	245	39.0	19.2
1840	1.9 – j6.8	1.7 – j3.3	250	39.8	19.5
1880	2.8 – j7.5	1.7 – j2.8	235	42.0	20.3

^[1] Z_S and Z_L defined in Figure 1.

^[2] At $P_{L(AV)} = 85 \text{ W}$.

Table 12. Typical impedance of main device at 1: 2.5 load

Measured load-pull data of main device; I_{Dq} = 1100 mA (main); V_{DS} = 28 V; pulsed CW (t_p = 100 μ s; δ = 10 %).

f	Z _S [1]	Z _L [1]	P _{L(3dB)} [2]	η _D [2]	G _p [2]
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)
1805	1.6 – j6.1	4.3 – j3.2	145	53.2	21.7
1840	1.9 – j6.8	4.2 – j2.9	145	51.7	21.7
1880	2.8 – j7.5	4.2 – j2.6	140	50.4	22.3

^[1] Z_S and Z_L defined in Figure 1.

Table 13. Typical impedance of peak device at 1:1 load

Measured load-pull data of peak device; I_{Dq} = 2200 mA (peak); V_{DS} = 28 V; pulsed CW (t_p = 100 μ s; δ = 10 %).

f	Z _S [1]	Z _L [1]	P _{L(3dB)} [2]	η _D [2]	G _p [2]
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)
1805	1.5 – j5.9	1.8 – j4.2	340	33.1	18.2
1840	1.9 – j6.3	1.7 – j3.9	350	33.8	18.7
1880	2.2 – j7.1	1.7 – j3.7	320	35.4	19.1

^[1] Z_S and Z_L defined in Figure 1.

Table 14. Off-state impedances of peak device

f	Z _{off}
(MHz)	(Ω)
1805	2.2 – j3.5
1840	1.1 – j1.7
1880	0.7 – j0.8

^[2] At $P_{L(AV)} = 85 \text{ W}$.

^[2] At $P_{L(AV)} = 85 \text{ W}$.

7.4 Test circuit

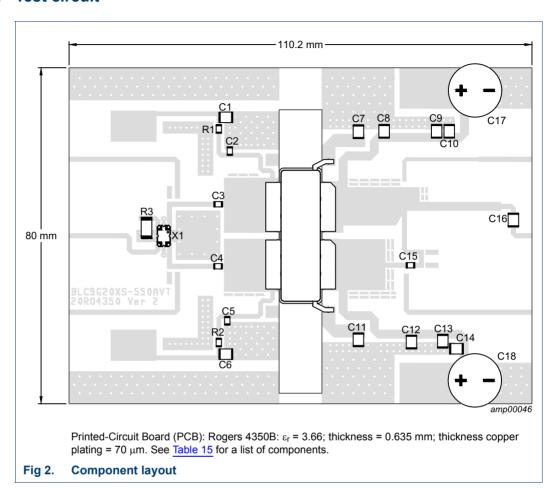


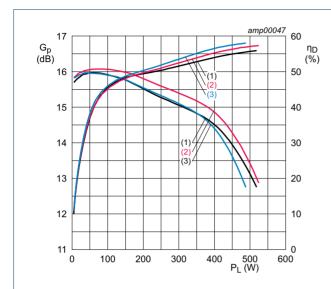
Table 15. List of components

See Figure 2 for component layout.

Component	Description	Value	Remarks
C1, C6, C7, C9, C10, C11, C13, C14	multilayer ceramic chip capacitor	4.7 μF, 50 V	Murata GRM32ER71H475KA88L
C2, C3, C4, C5	multilayer ceramic chip capacitor	20 pF	ATC 100A
C8, C12	multilayer ceramic chip capacitor	20 pF	ATC 100B
C15	multilayer ceramic chip capacitor	10 pF	ATC 100A
C16	multilayer ceramic chip capacitor	10 pF	ATC 100B
C17, C18	electrolytic capacitor	470 μF, 63 V	
R1, R2	resistor	2.00 Ω, 1 %	SMD 0805
R3	resistor	50 Ω, 25 W	Anaren C16A50Z4
X1	hybrid coupler	2 dB, 90°	Anaren Xinger III, X3C20F1-02S

7.5 Graphical data

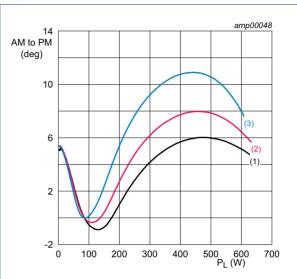
7.5.1 Pulsed CW



 V_{DS} = 28 V; I_{Dq} = 1000 mA; $V_{GS(amp)peak}$ = 0.75 V; t_p = 100 $\mu s;$ δ = 10 %.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 3. Power gain and drain efficiency as function of output power; typical values



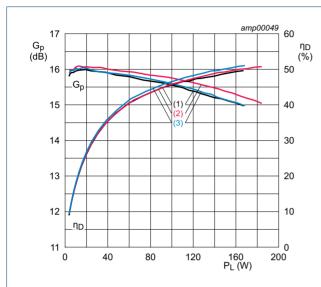
 V_{DS} = 28 V; I_{Dq} = 1000 mA; $V_{GS(amp)peak}$ = 0.75 V.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 4. Normalized AM to PM as a function of output power; typical values

7.5.2 1-Carrier W-CDMA

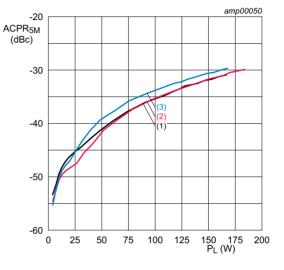
PAR = 9.6 dB per carrier at 0.01 % probability on the CCDF; 3GPP test model 1 with 64 DPCH (100 % clipping).



 V_{DS} = 28 V; I_{Dq} = 1000 mA; $V_{GS(amp)peak}$ = 0.75 V.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

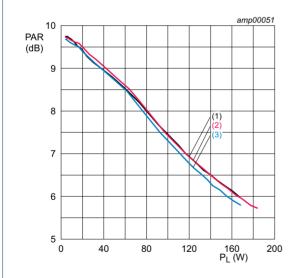
Fig 5. Power gain and drain efficiency as function of output power; typical values



 $V_{DS} = 28 \text{ V}$; $I_{Dq} = 1000 \text{ mA}$; $V_{GS(amp)peak} = 0.75 \text{ V}$.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

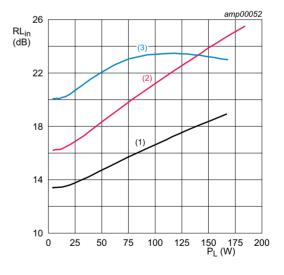
Fig 6. Adjacent channel power ratio (5 MHz) as a function of output power; typical values



 V_{DS} = 28 V; I_{Dq} = 1000 mA; $V_{GS(amp)peak}$ = 0.75 V.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 7. Peak-to-average power ratio as a function of output power; typical values



 V_{DS} = 28 V; I_{Dq} = 1000 mA; $V_{GS(amp)peak}$ = 0.75 V.

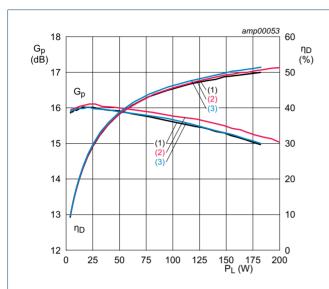
- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 8. Input return loss as a function of output power; typical values

BLC9G20XS-550AVT

7.5.3 2-Carrier W-CDMA

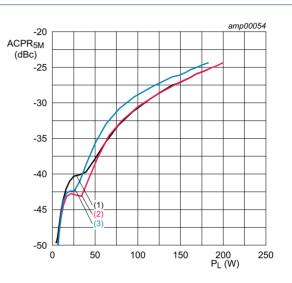
PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1 with 64 DPCH (46 % clipping).



 V_{DS} = 28 V; I_{Dq} = 1000 mA; $V_{GS(amp)peak}$ = 0.75 V.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

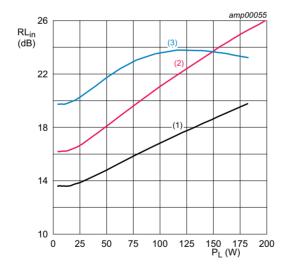
Fig 9. Power gain and drain efficiency as function of output power; typical values



 $V_{DS} = 28 \text{ V}$; $I_{Dq} = 1000 \text{ mA}$; $V_{GS(amp)peak} = 0.75 \text{ V}$.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 10. Adjacent channel power ratio (5 MHz) as a function of output power; typical values

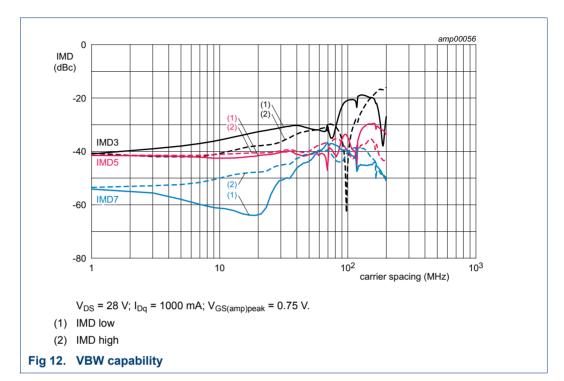


 V_{DS} = 28 V; I_{Dq} = 1000 mA; $V_{GS(amp)peak}$ = 0.75 V.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 11. Input return loss as a function of output power; typical values

7.5.4 2-Tone VBW



8. Package outline

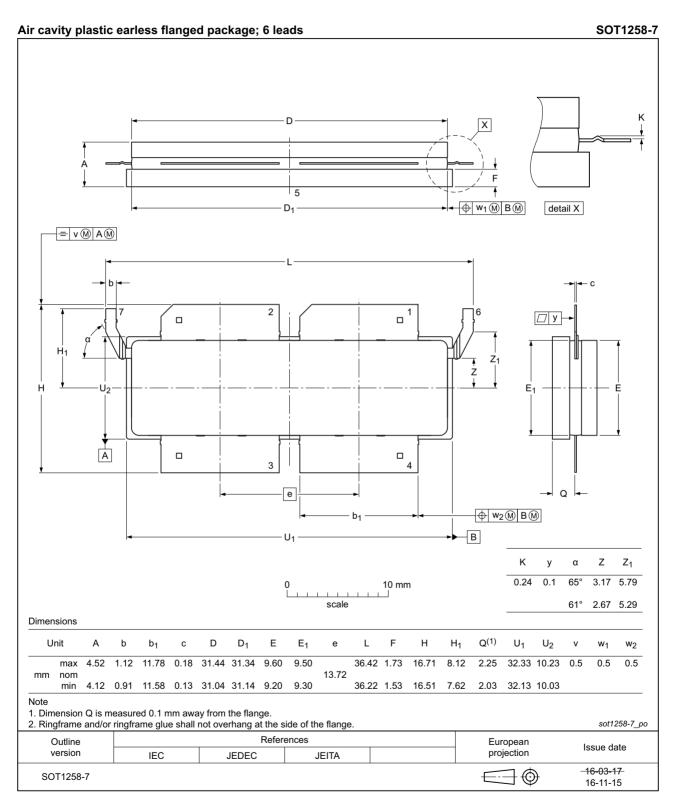


Fig 13. Package outline SOT1258-7

9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

Table 16. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C2A [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

- [1] CDM classification C2A is granted to any part that passes after exposure to an ESD pulse of 500 V, but fails after exposure to an ESD pulse of 750 V.
- [2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V, but fails after exposure to an ESD pulse of 4000 V.

10. Abbreviations

Table 17. Abbreviations

Acronym	Description
3GPP	3rd Generation Partnership Project
AM	Amplitude Modulation
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DPCH	Dedicated Physical CHannel
ESD	ElectroStatic Discharge
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
MTF	Median Time to Failure
ОВО	Output Back Off
PAR	Peak-to-Average Ratio
PM	Phase Modulation
SMD	Surface Mounted Device
VBW	Video BandWidth
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

11. Revision history

Table 18. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLC9G20XS-550AVT v.2	20161202	Product data sheet	-	BLC9G20XS-550AVT v.1
Modifications:	Figure 13 on page 12: updated package outline drawing SOT1258-7			
	Section 9 on page 13: updated Handling information			
BLC9G20XS-550AVT v.1	20160513	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.ampleon.com.

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13. Contact information

For more information, please visit: http://www.ampleon.com

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